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Renesas Technology Corp. Customer Support Dept. April 1, 2003



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Silicon NPN Epitaxial

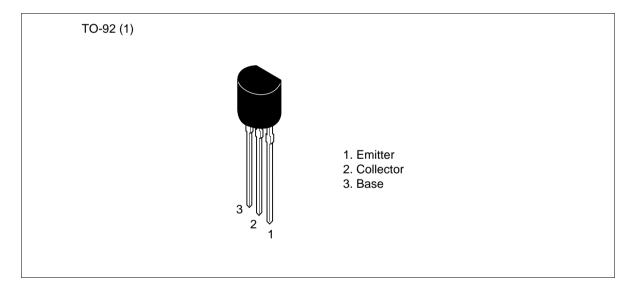


ADE-208-1048 (Z) 1st. Edition Mar. 2001

Application

- Low frequency amplifier
- Complementary pair with 2SA673 and 2SA673A

Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

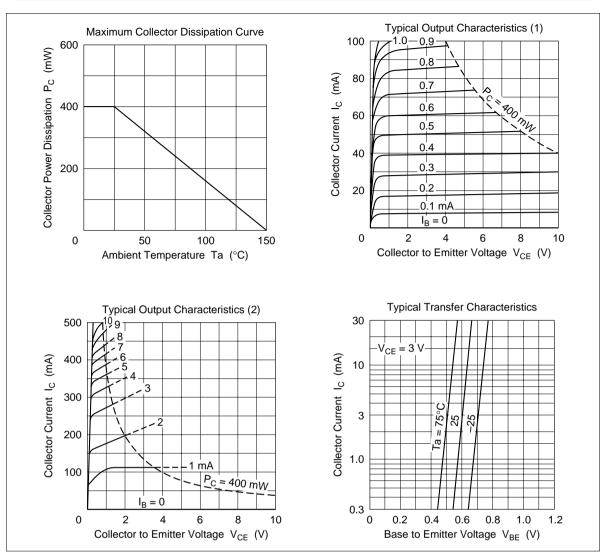
Item	Symbol	2SC1213	2SC1213A	Unit
Collector to base voltage	V _{CBO}	35	50	V
Collector to emitter voltage	V _{CEO}	35	50	V
Emitter to base voltage	V _{EBO}	4	4	V
Collector current	Ι _c	500	500	mA
Collector power dissipation	Pc	400	400	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

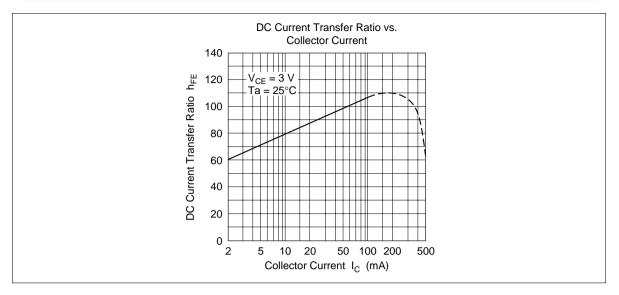
Electrical Characteristics (Ta = 25°C)

		2SC1	213		2SC1213A				
ltem	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	35	_	_	50	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	35	_		50	_		V	$I_c = 1 \text{ mA}, R_{BE} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	4		_	4	—	_	V	$I_{\rm E} = 10 \ \mu {\rm A}, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	—	_	0.5	—	_	0.5	μA	$V_{CB} = 20 \text{ V}, \text{ I}_{E} = 0$
DC current tarnsfer ratio	h_{FE}^{*1}	60	_	320	60	_	320		V_{ce} = 3 V, I_c =10 mA
	h_{FE}	10		—	10	—	_		$V_{ce} = 3 V,$ $I_c = 500 mA^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	0.2	0.6	—	0.2	0.6	V	$I_{c} = 150 \text{ mA},$ $I_{B} = 15 \text{ mA}^{*2}$
Base to emitter voltage	V_{BE}	—	0.64	—	—	0.64		V	$V_{ce} = 3 \text{ V}, I_c = 10 \text{ mA}$
Notes: 1. The 2SC1213 and 2SC1213A are grouped by h_{FE} as follows.									

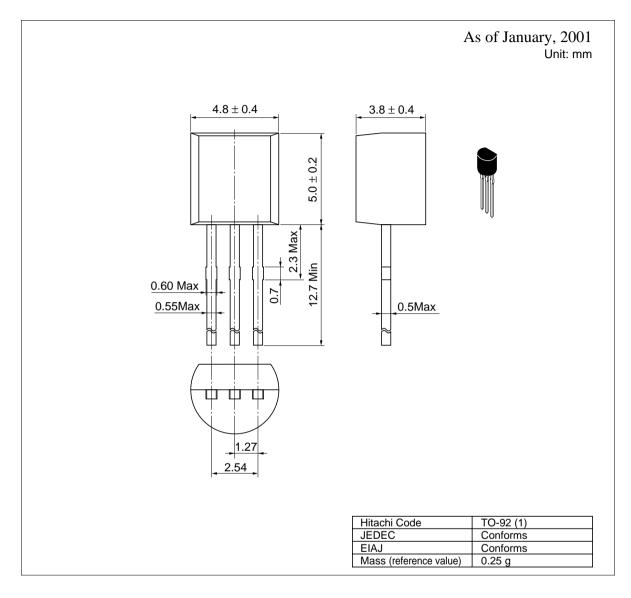
otes: 1. The 2SC1213 and 2SC1213A are grouped by n_{FE} as follows.

2.	Pulse test			
В	С	D		
60 to 120	100 to 200	160 to 320		





Package Dimensions



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